

# SolderStar PRO - Reflow Profiling Solutions



The package includes an ultra compact datalogger featuring the unique 'SmartLink' connector system, combined with a heatshield and thermocouple adapter to provide the number of measurement channels required.

Future upgrading or servicing is a simple and cost effective procedure, with only the Thermocouple Adapter needing to be changed to allow 6,9,12 or 16 Type-K measurement versions.

The SmartLink' concept allows high measurement channel configurations, while maintaining a small footprint and quick connection to a range of accessories for capture of profile and SPC information from reflow, wave/selective and vapour phase soldering processes.

A comprehensive suite of software includes profile analysis, data management, profile simulations and integrated SPC charting tools. This easy to use system is ideal for manufacturers and EMS providers who require rapid profile setup followed by periodic measurements to control their solder process quality.

# **System Advantages**

- Compact size for profling of narrow PCB formats or ovens with low tunnel clearance
- Support for 6 to 16 measurement channels for profiling of the most complex PCB assemblies
- Unique SmartLink connection system provides
   quick datalogger connection to a range of products and accessories
- Software tools including profile analysis and simulation, plus integrated SPC management features
- Connectivity via standard USB cables or 2.4Ghz
   Wireless Telemetry
- Extendable for control of wave / selective or vapour phase soldering

# **Datalogger**

### **Technical Data**

Size/Weight 125mm x 52mm x 9mm,110g

Channels 6,9,12 or 16 Channel Versions Available

Memory 120,000 Memory Points
Sampling 0.1s to 10 Minutes
Measurement Range -150 to 600 °C

Accuracy  $\pm 0.5 \, ^{\circ}\text{C}$  Resolution  $\pm 0.02 \, ^{\circ}\text{C}$ 

Max. Internal Temperature +85 °C (Auto Shutdown on over temp.)

Power Rechargeable High Temperature Nimh

Communications USB (Type A - Mini B) or 2.4Ghz Wireless

Thermocouples Type K, EN 05842:1993 Class 1 / ANSI MC 96.1

#### Heatshield

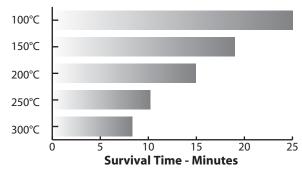
Material Stainless Steel

Size (LxWxH)

6/9 Channel Version: 310mm x 80mm x 25mm
12 Channel Version: 310mm x 104mm x 25mm

16 Channel Version: 330mm x 146mm x 25mm

#### **Thermal Protection Duration**



Other heatshield sizes are available for special process requirements.

# **Wireless Telemetry Option**

Frequency 2.4GHZ Transceiver

Channels 128 Individual Channels

Protocol Zigbee PRO - Duplex Transmission

#### **Software**

Compatibility Windows™ XP Vista/Windows 7/8/10

32 & 64 Bit

Language Support English, French, German, Italian,

Portuguese, Spanish & Chinese

For demonstration software visit www.solderstar.com

# **Standard Equipment**

- SolderStar PRO datalogger
- Thermocouple Adapter
- 25mm Lead Free capable heatshield
- · Type K thermocouples
- PC Analysis software
- Hard copy manual + 1 Year calibration certificate
- · Equipment case

# **Optional Reflow Equipment**

- AUTOSeeker Profiler Optimisation software
- 2.4Ghz Wireless Telemetry
- Deltaprobe Oven Verification fixture
- Adjustable Reflow Carrier

### **Additional Process Support**



**REFLOW • WAVE • VAPOUR** 

A range of process specific accessories are available to extend the system for use with Reflow, Wave/Selective Soldering and Vapour Phase processes.

Specification subject to change without notification

# For more information contact your regional Solderstar office



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